

L Number	Hits	Search Text	DB	Time stamp
1	0	((underfill or encapsulant) adj (comprising or comprises or consisting)) adj dam	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/28 15:16
-	172	angle and (chip or semiconductor) and underfill	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/28 11:27
-	2348	(angle same (resin or encapsulant)) and (chip or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/28 11:28
-	1202	((angle same (resin or encapsulant)) and (chip or semiconductor)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/05/28 13:20
-	1	("5541450").PN.	USPAT	2002/05/28 15:03